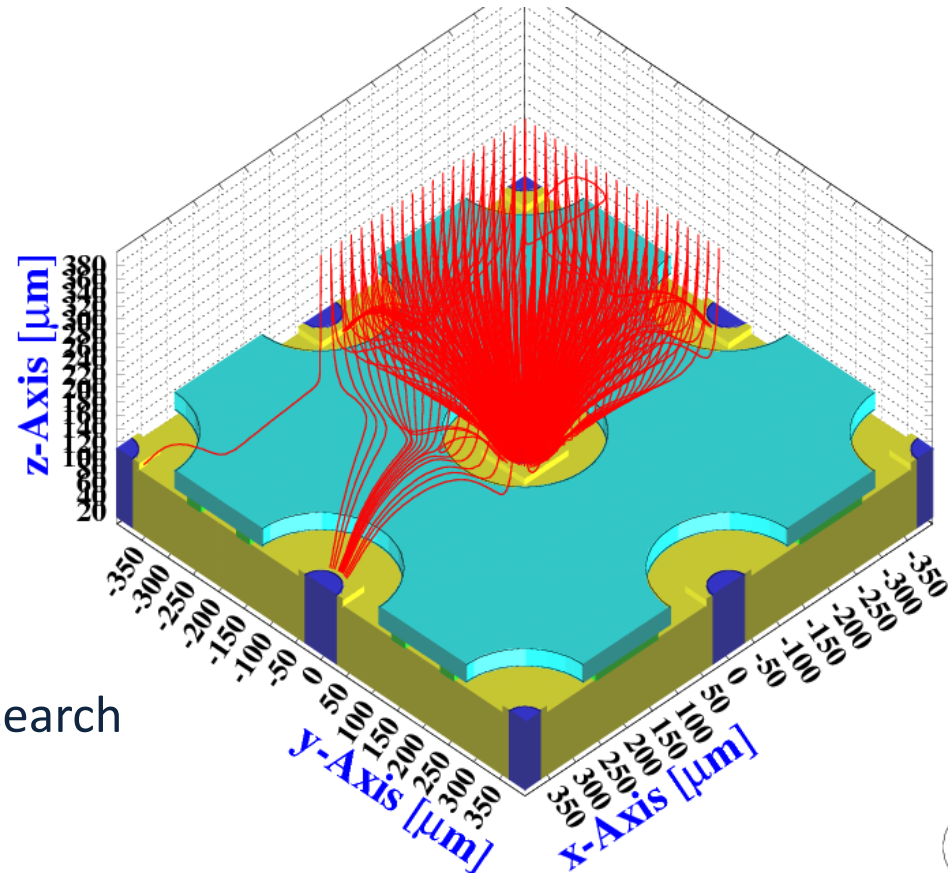


# Kobe University Particle Physics Labo. MPGD ( $\mu$ -PIC) group



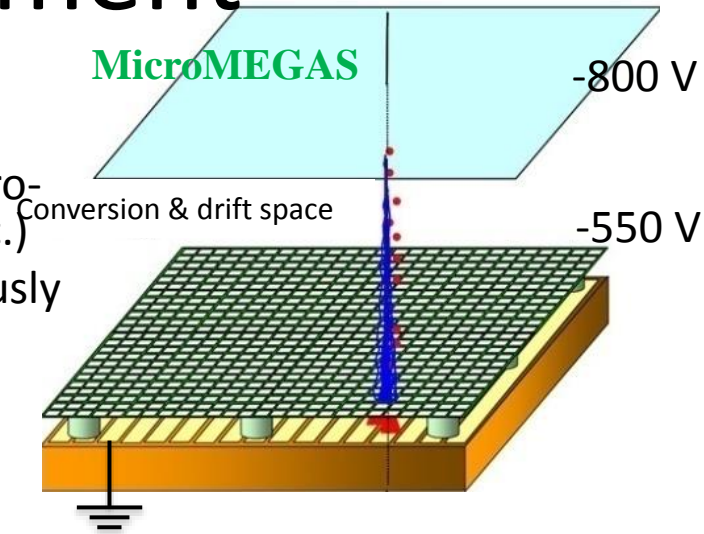
29/08/2014

KUBEC International workshop on DM search

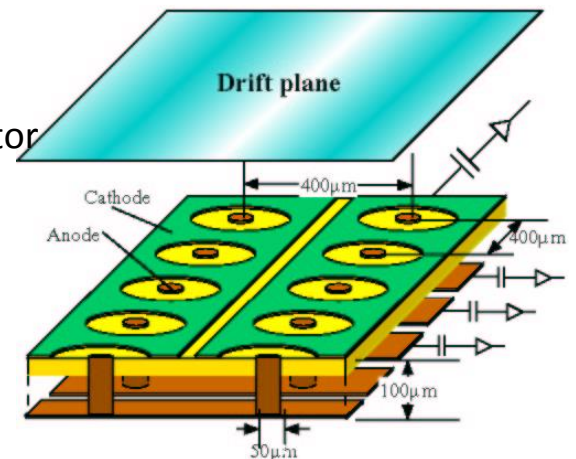
Atsuhiko Ochi

# MPGD Development

- What is MPGD ?
  - **Micro Pattern Gaseous Detector**
  - Recent technology for gaseous detector, using micro-patterning (photo-lithography, laser patterning, etc.)
  - Key technology for realizing followings simultaneously
    - high position resolution ( $< 100 \mu\text{m}$ )
    - high rate capacitance ( $> 10^6 \text{ counts/mm}^2$ )
    - Large area ( $\sim$  a few meter size)
    - Mass productivity (close to PCB industrial technology)
- R&D in Kobe PP labo.
  - **$\mu$ -PIC**
    - Development of imaging gas detector using resistive electrodes for stable operation.
    - Application for Dark Matter search (NEWAGE)
    - Application for ATLAS phase-II upgrade, High  $\eta$  muon detector
  - **MicroMEGAS**
    - For muon spectrometer in ATLAS phase-I upgrade
    - Developing new electrodes material, and operation test
  - **RE-GEM**
    - Stable, and spark free GEM (Just start to develop)



**Micro Pixel Chamber**



# Common R&D themes for MPGDs

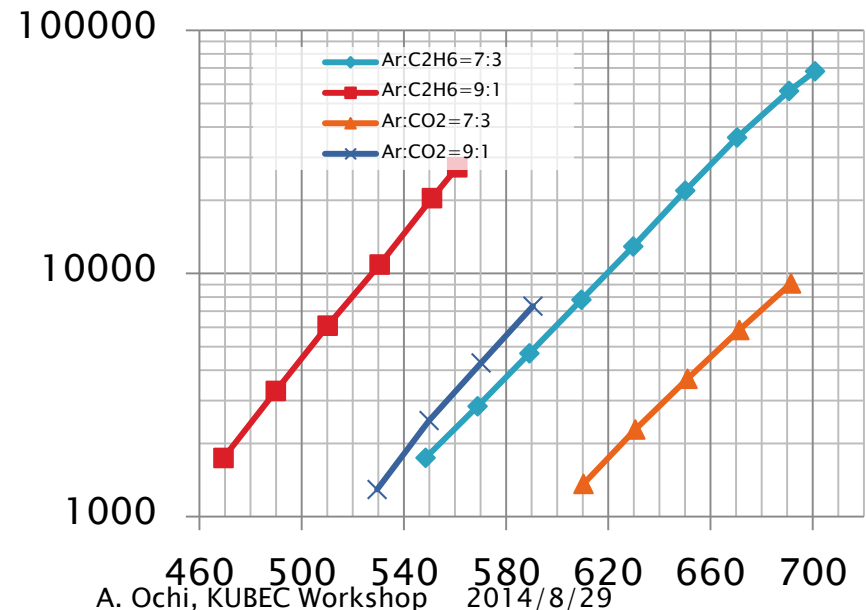
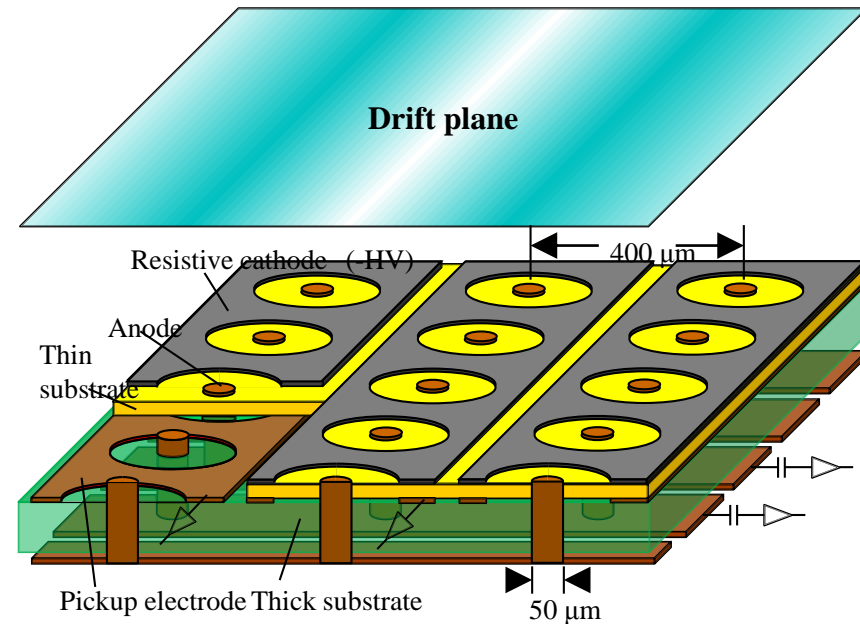
- ▶ Understanding for the MPGD operation
  - We need to share our experiences and information.
- ▶ Robustness for the spark
  - It was most critical problem.
- ▶ Large area production
  - It was big theme in RD51, depending on applications.
- ▶ Multi channel readout
  - KEK-DTP ASIC group and RD51 have already developed the system

# $\mu$ -PIC with resistive electrodes



# $\mu$ -PIC with resistive cathodes with capacitive readout

- ▶ The cathodes of  $\mu$ -PIC is formed by resistive material.
- ▶ Large current from spark reduce the e-field, and spark is quenched.
- ▶ Signal from low energy deposit will be observed with higher gas gain
- ▶ This design provides one promising possibility of **MIP detector under hadronic background**
- ▶ **It takes enough gain ( $\sim 7 \times 10^5$ , with Ar+ethane)**
  - ▶ This work was followed by KAKENHI supporting research (2011–2014)



# Process for manufacturing

(a) Start from double sided kapton



(b) Thick plating on surface (~ 50µm)



(c) Exposure using double side mask



(d) Developing resist



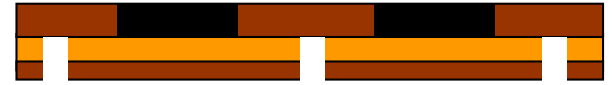
(e) Etching for the pattern



(f) Fill the resistive polyimide & cure



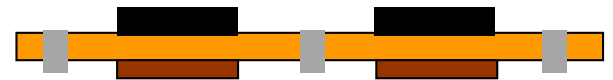
(g) Polishing the surface



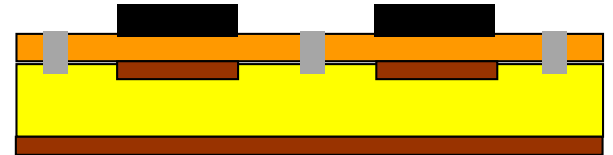
(h) Plating the anode pin



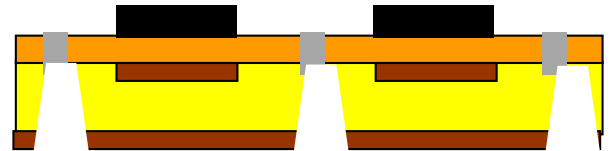
(i) Etching the metal layer



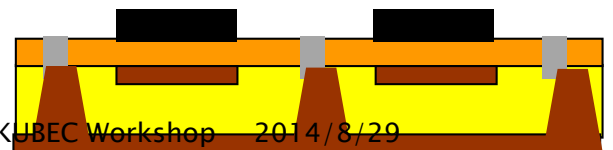
(j) Adhering the thick layer



(k) Laser drilling for anode pin

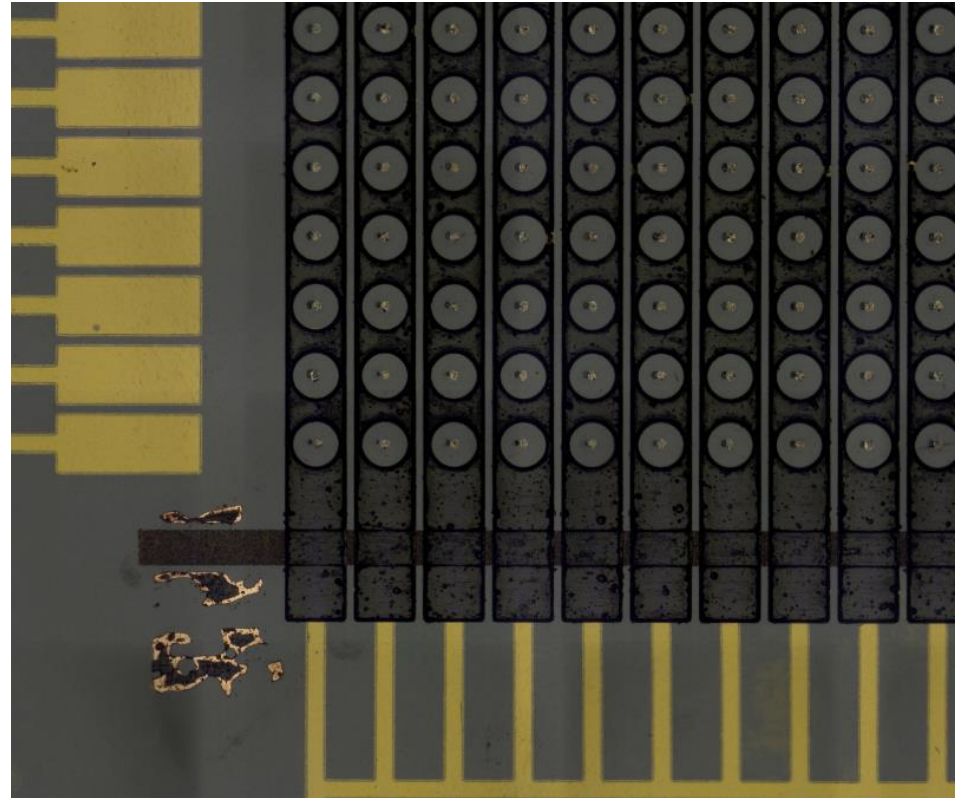
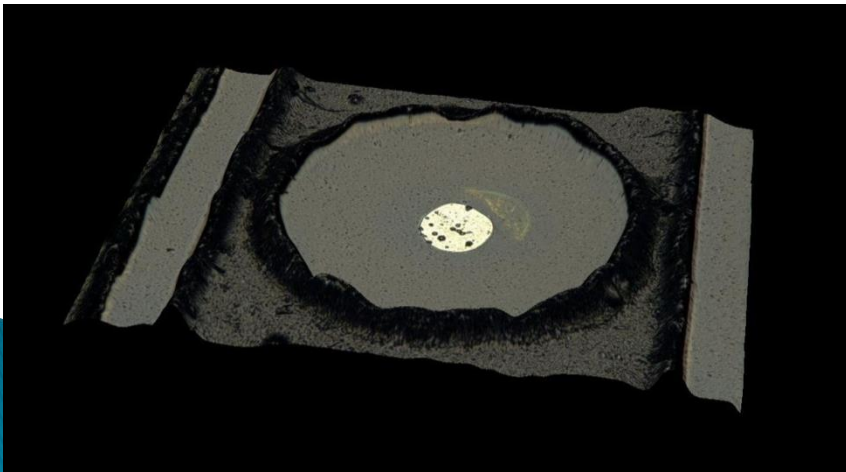


(l) Plating anode pin



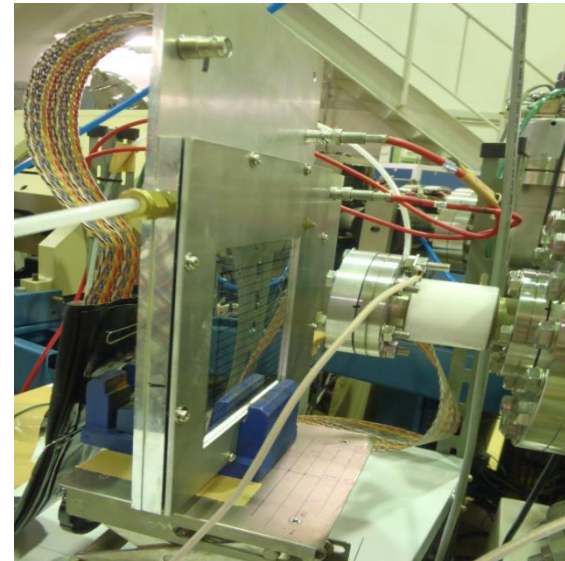
# Micro scope picture of a prototype (RC27)

- Delivered at July 2012
- Very good accuracy (compared with previous samples)
- Surface resistivity
  - About  $50\text{M}\Omega$  / strip (10cm)



# Spark test using fast neutron

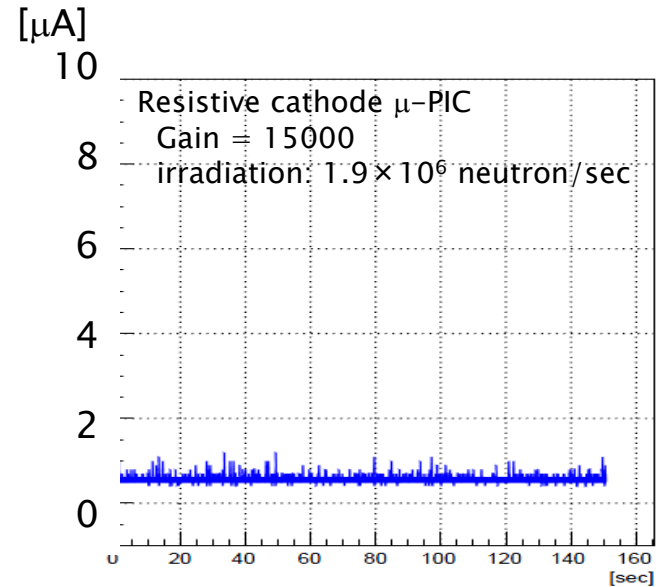
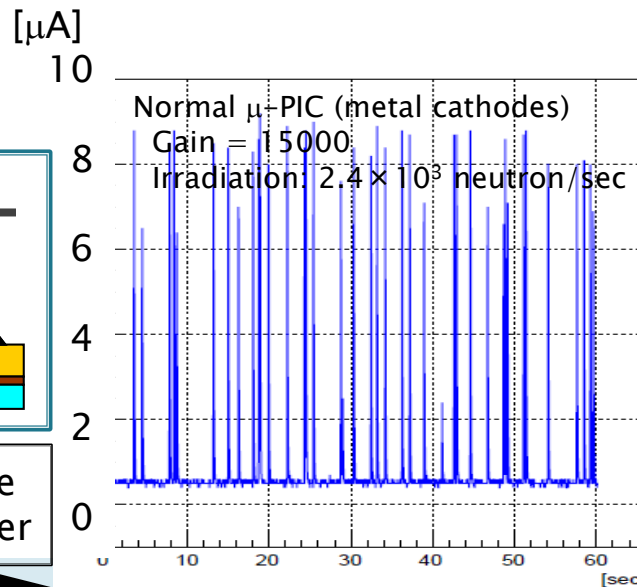
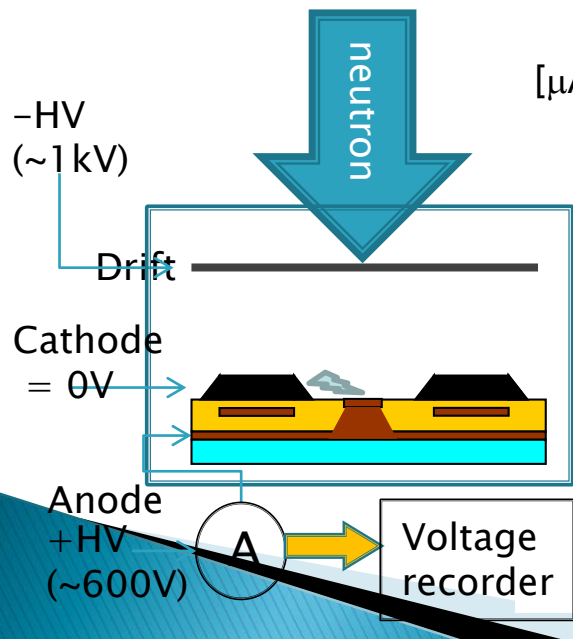
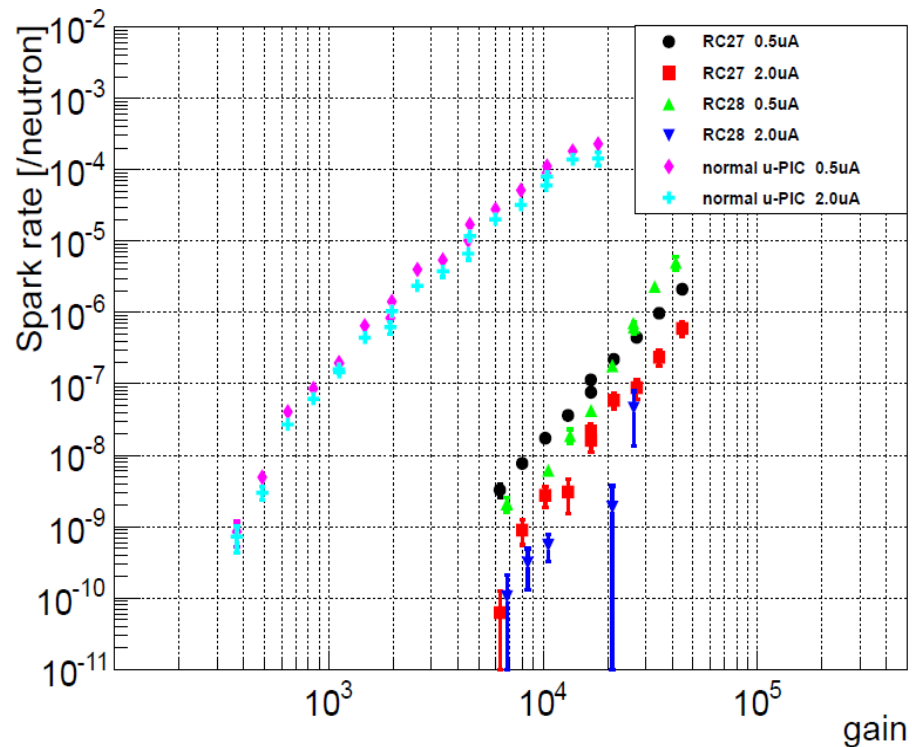
- ▶ A few MeV – few tenth MeV neutron will produce recoiled nucleon inside detectors
  - That produce great amount of energy deposit (a few MeV/mm<sup>2</sup>) in gaseous volume.
- ▶ The concerned problem for gas detector
  - “Raether limit” ... the electron cluster more than 10<sup>7-8</sup> cause the detector to discharge.
- ▶ We can evaluate the spark probability for HIP by measuring the spark rate dependencies on neutron irradiation
- ▶ Neutron source
  - Tandem nucleon accelerator (3MeV deuteron) + Beryllium target. (Kobe University, Maritime dept.)
  - $d + {}^9\text{Be} \rightarrow n + {}^{10}\text{B}$
  - Neutron energy: mainly 2MeV





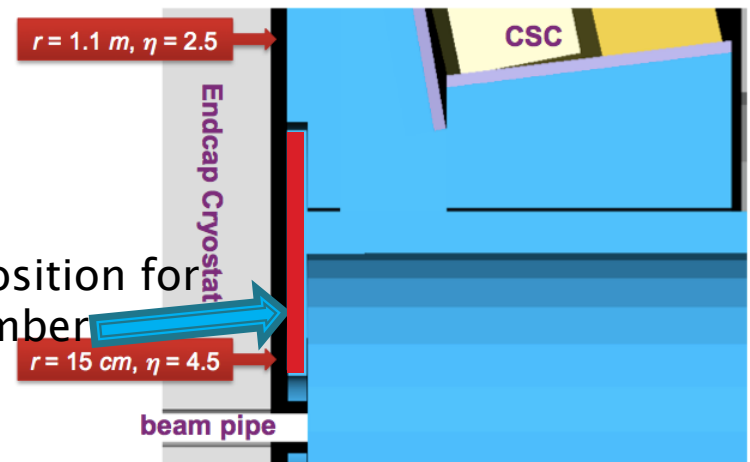
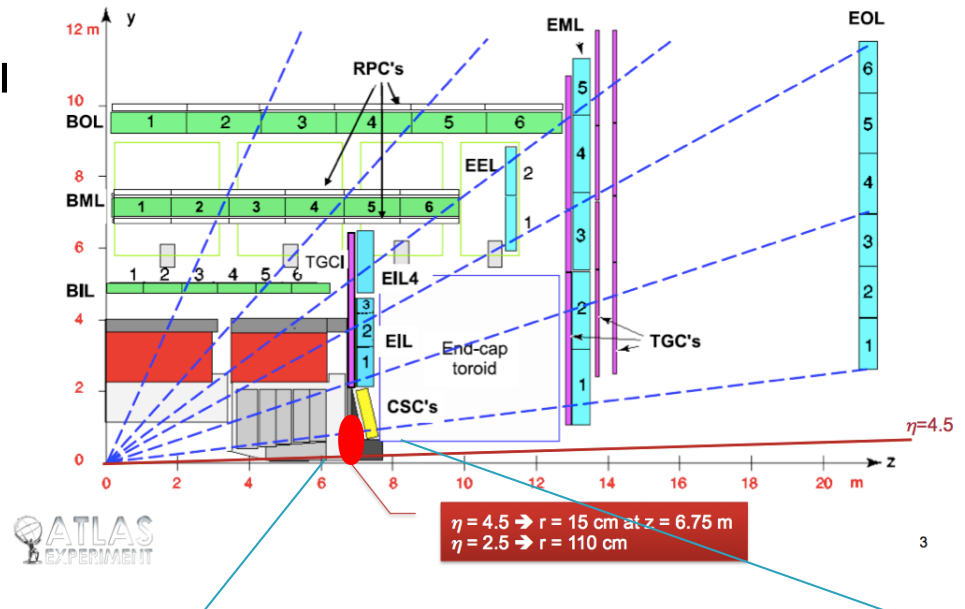
# Results of spark reduction test

- ▶ HV current on anodes are monitored while neutrons are irradiated
- ▶ We found **strong spark reduction using resistive cathode !!**



# Application idea for ATLAS upgrade (phase-II)

- ▶ Very High  $\eta$  muon detector
  - $2.5 < \eta < 4.5$
- ▶ Improving High  $p_T$  acceptance
  - + a few tens %
- ▶ Available position:
  - 5cm width beside endcap cryostat
- ▶ High rate dose
  - $10^{16} \text{n/cm}^2$
- ▶ Required granularity
  - $100\mu\text{m} \times 100\mu\text{m}$
- ▶ → Basic study is started by  $\mu$ -PIC



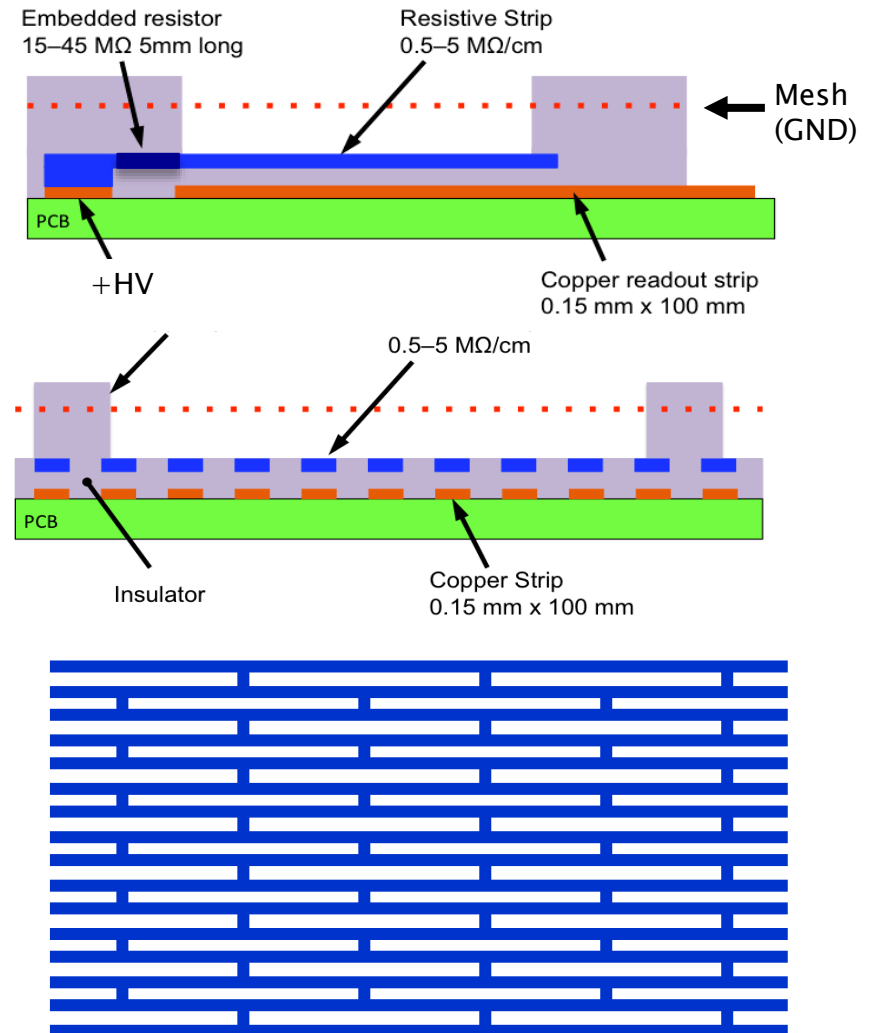
Candidate position for forward chamber

# MicroMEGAS for ATLAS NSW

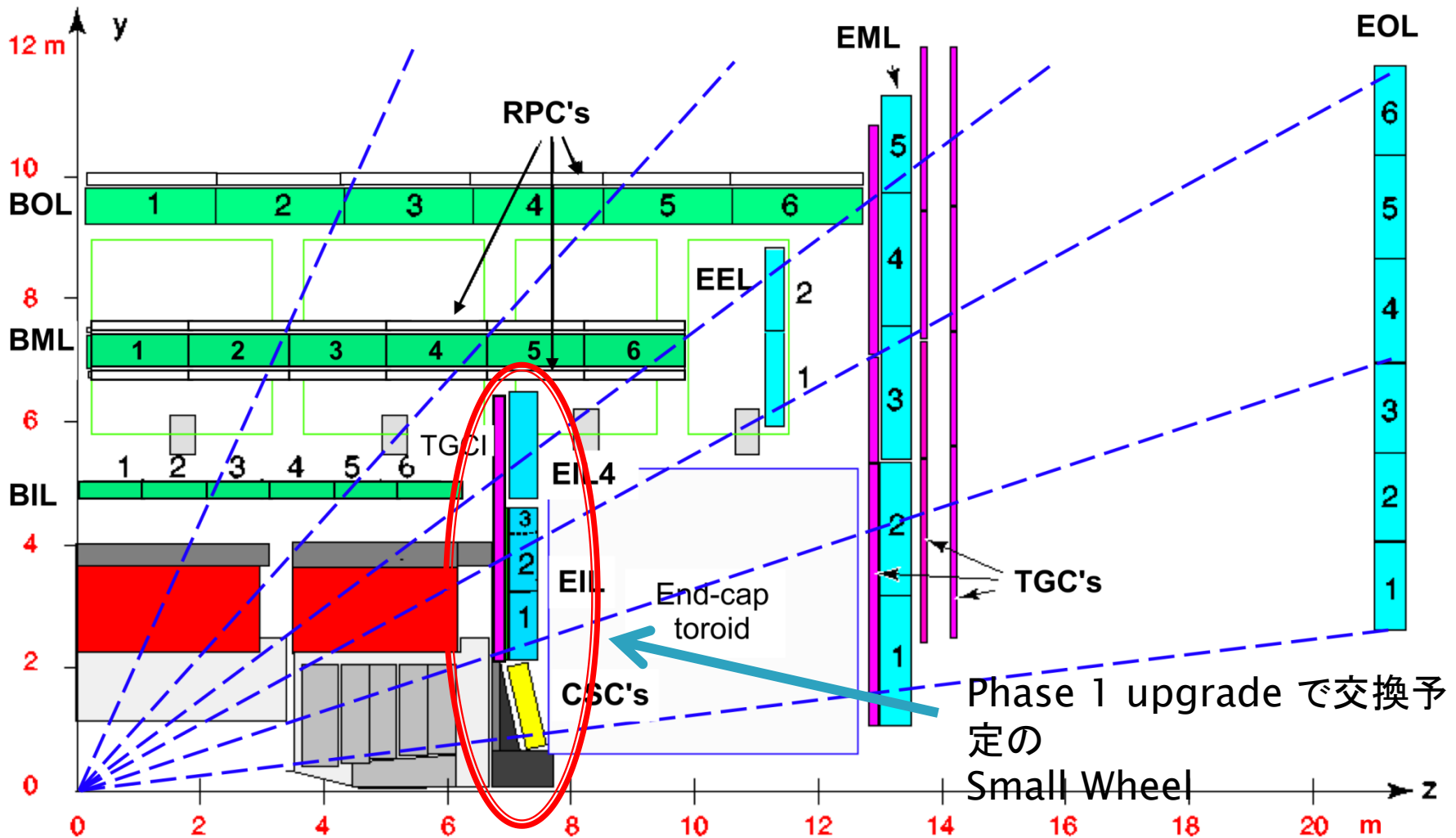


# Requirements for ATLAS NSW MM

- ▶ High position resolution for one dimension
  - $< 100 \mu\text{m}$  for eta direction.  
(Resolution of a few cm is allowed for second coordinate.)
- ▶ Tolerant for high rate HIP particles
  - $\sim 5\text{kHz}/\text{cm}^2$
- ▶ **Resistive layer should be formed as strips**
- ▶ Resistivity:  $\sim 20\text{M}\Omega/\text{cm}$ 
  - To protect from spark
- ▶ Mass production should be available, with large size (1m)
  - $\sim 2000$  board should be produced in half year.
- ▶ Low cost



# The Muon Spectrometer



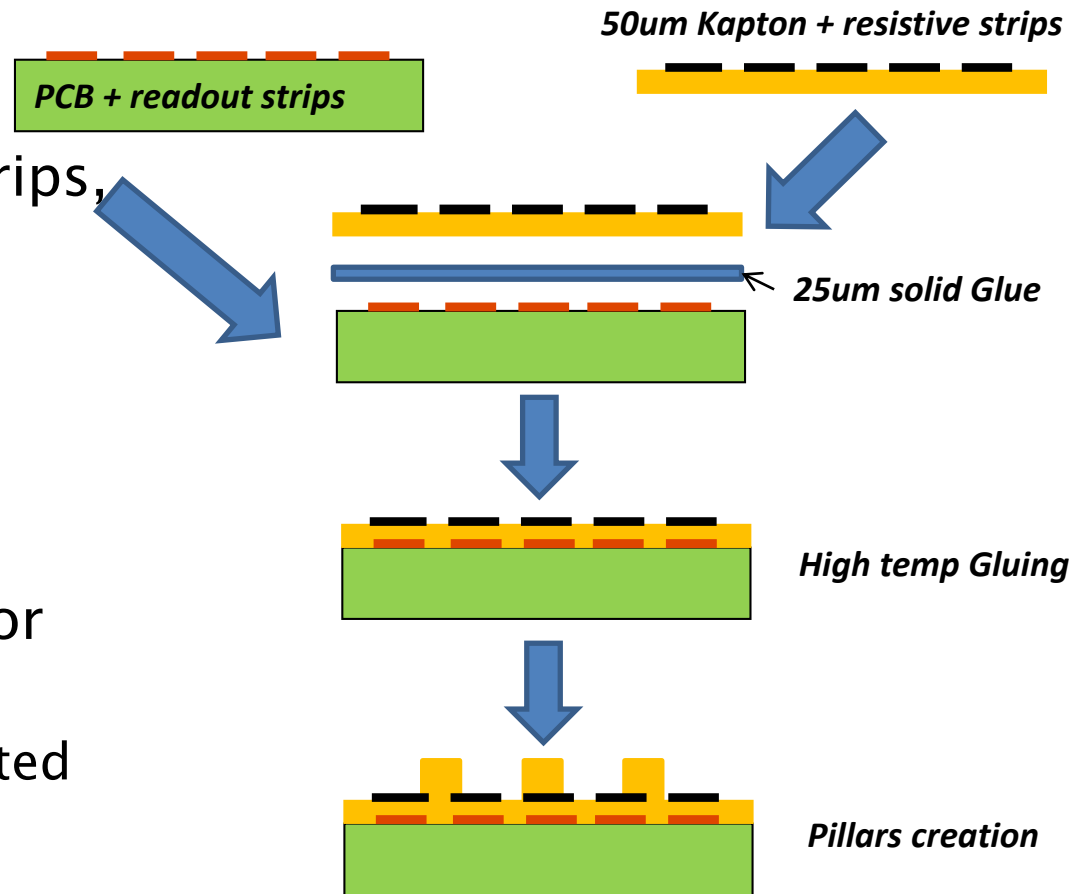
# Resistive strips foil

## ▶ Pattern

- Along with readout strips, with inter connect pattern.
  - 300–350  $\mu\text{m}$  width
  - 415–450  $\mu\text{m}$  pitch

## ▶ Resistivity

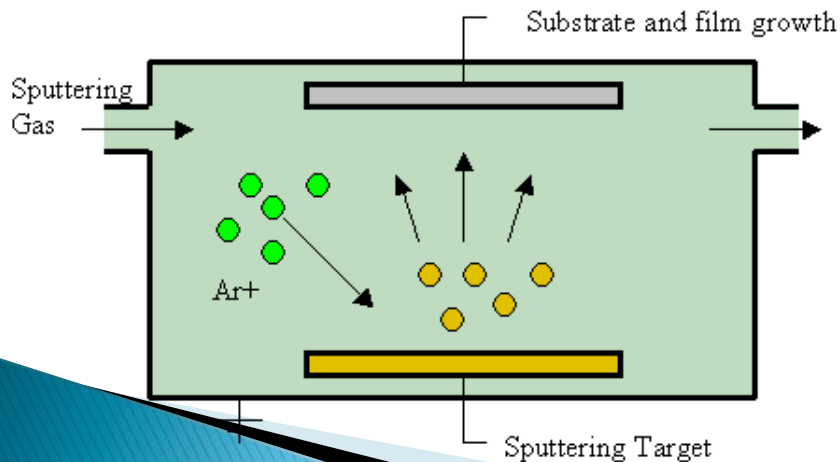
- Typically,  $20\text{M}\Omega/\text{cm}$  for each strips
  - $\pm 20\%$  will be accepted as “Grade A”
  - Maximum allowance:  $-67\% / +200\%$  (Grade C”)



# Candidates for production

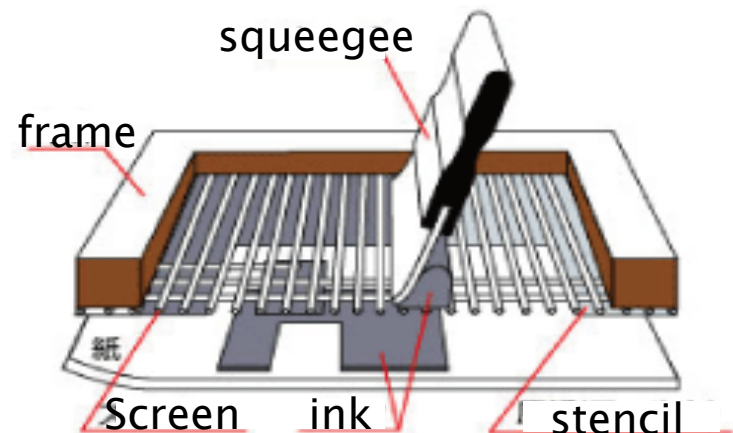
## ▶ Sputtering+liftoff

- Pros.
  - Large area ( $>2\text{m}$ )
  - Fine pattern ( $<100\mu\text{m}$ )
  - Uniform resistivity
  - Strong attachment on substrate
- Cons.
  - Production speed (Now, it will be OK, next slide)
  - High cost



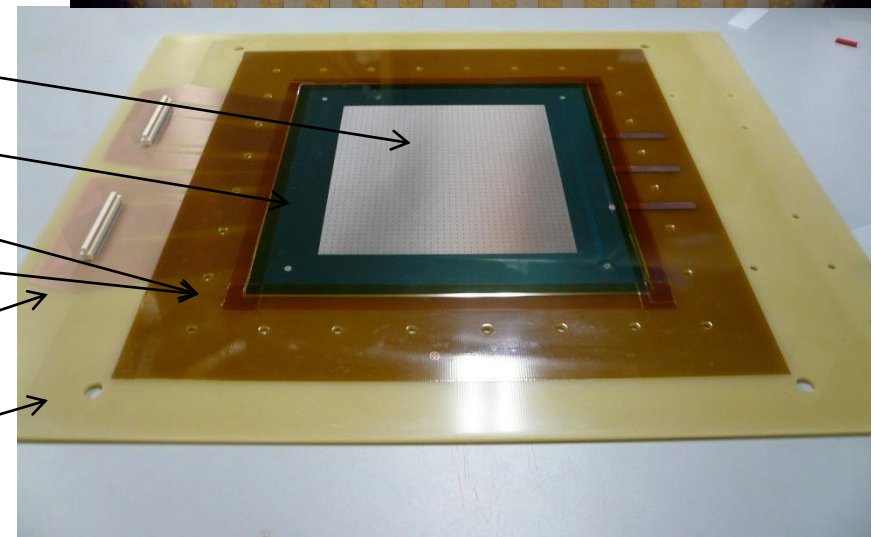
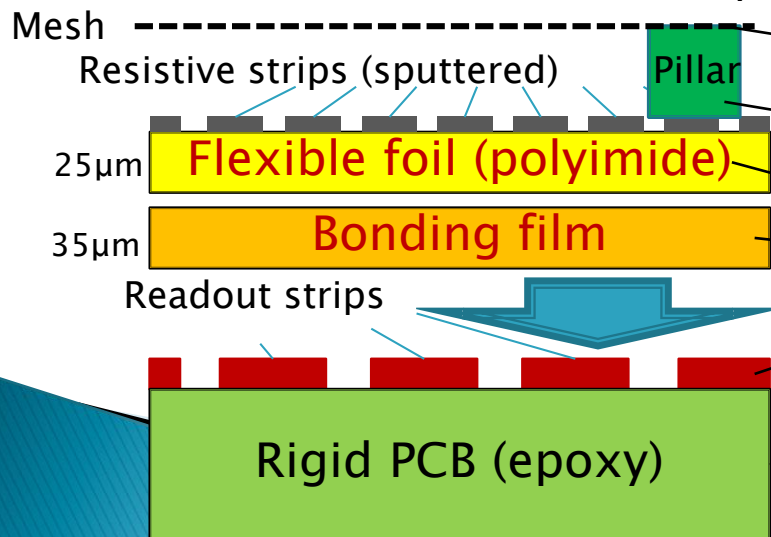
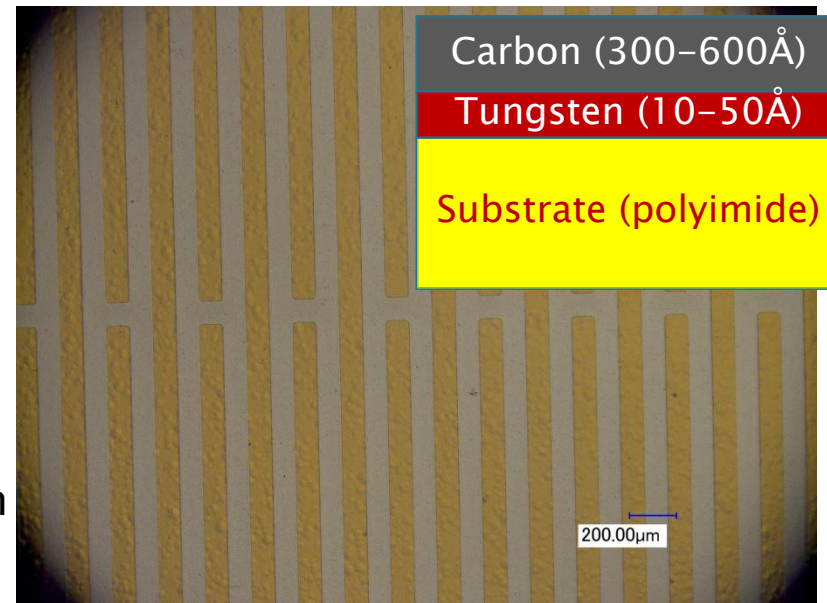
## ▶ Screen printing

- Pros.
  - Large area ( $>2\text{m}$ )
  - Fast production speed
  - Low cost for mass production
- Cons.
  - Stability of resistivity
  - Thick pattern ( $\sim 20\mu\text{m}$ )
  - Lower tolerance for breakdown for high voltage



# Prototype of small MicroMEGAS

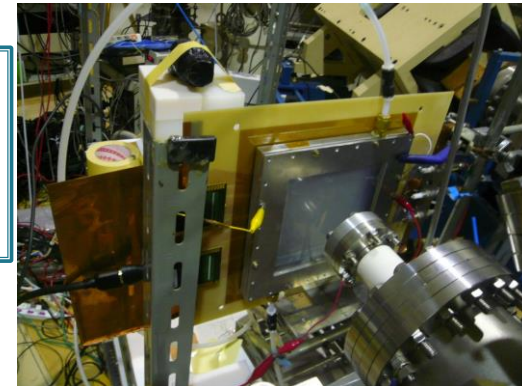
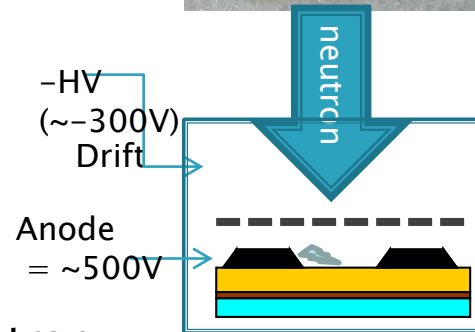
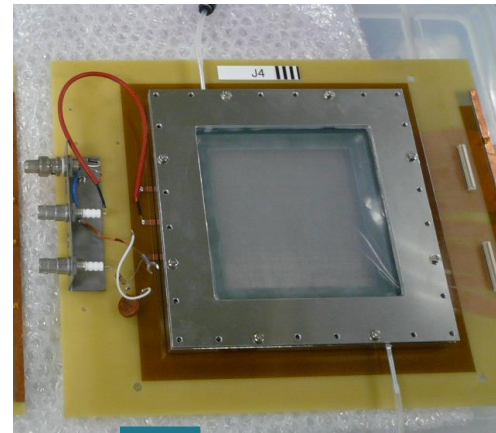
- ▶ June, 2013 – bulk MM
  - Surface resistivity:  $10\text{M}\Omega/\text{sq.}$ 
    - With  $300\text{\AA}$  carbon +  $50\text{\AA}$  W
- ▶ November, 2013 – floating mesh
  - Surface resistivity:  $500\text{k}\Omega/\text{sq.}$ 
    - With  $3600\text{\AA}$  carbon
- ▶ The readout board consists of
  - Readout strips (Rigid PCB).
  - Resistive strip foil (Polyimide film).
  - Fine strip pitch of  $200\ \mu\text{m}$  is formed on  $25\ \mu\text{m}$  polyimide foil.
  - Substrate thickness :  $60\ \mu\text{m}$ .



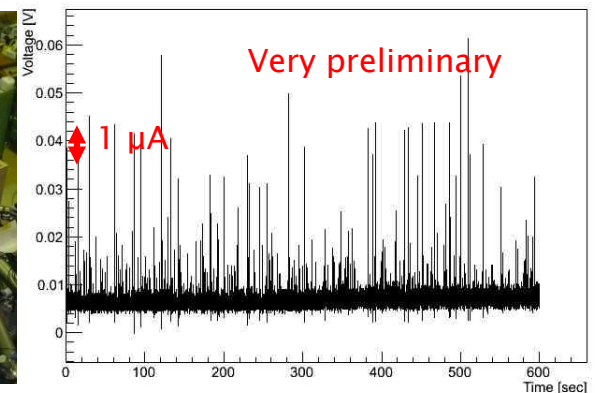
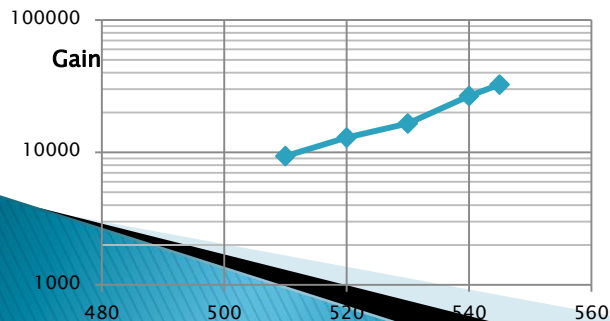


# Fast neutron test

- ▶ Beamtests for sputtering MPGD
- ▶ Gain curve of 5.9 keV X-ray.
  - Drift = -300V
  - Drift spacing: 5mm
  - Gas: Ar(93%) + CO2(7%)
- ▶ Fast Neutron test for spark probability
  - @Kobe Univ.
    - 17-23 Jun. 2013
    - 20-27 Jan. 2014
  - HV current log under intense neutron.
    - Neutron intense :  $\sim 10^5$  cps/cm<sup>2</sup>.
    - 0.01V correspond to 1  $\mu$ A
    - $\sim 600$ nA of base current was found while beam ON.



/Users/ochi/Documents/Work/mpgd/J4/current\_monitor/run231708.txt

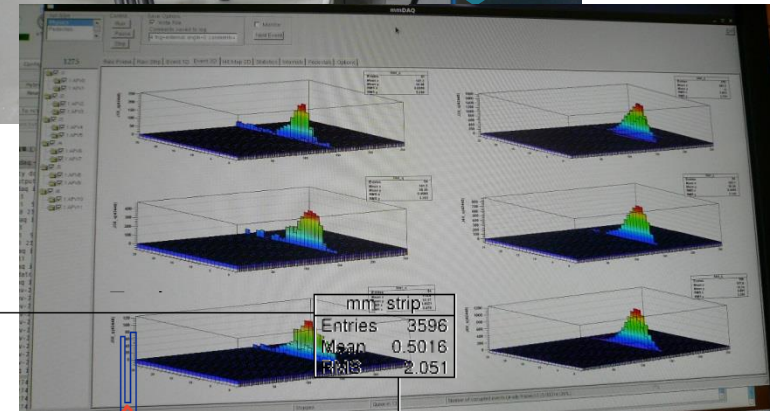
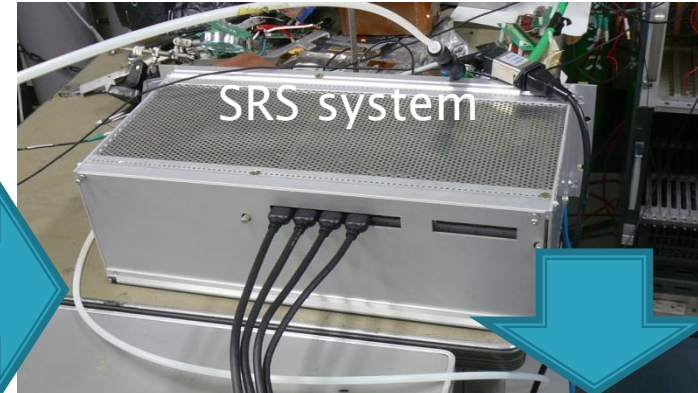
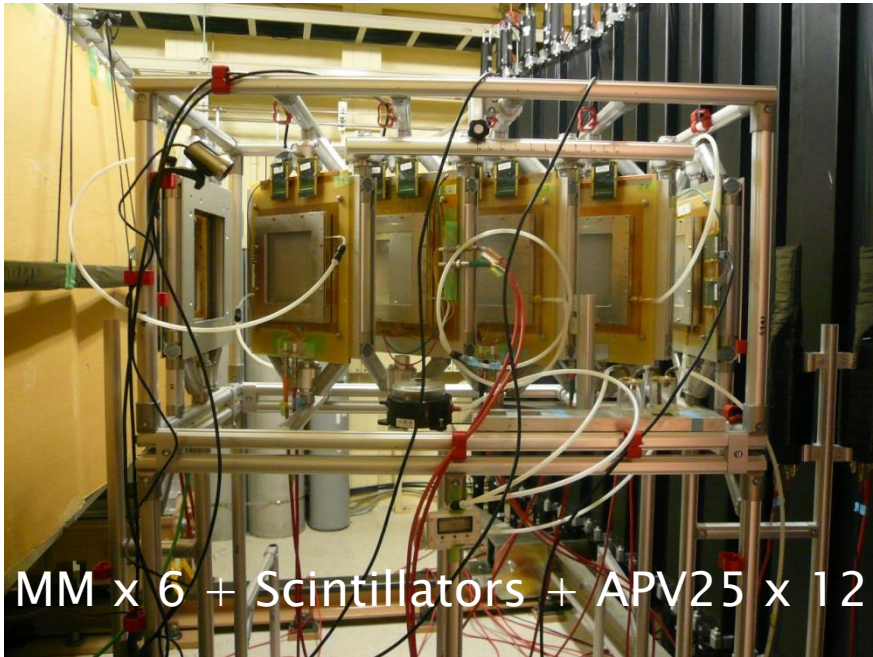


# After sparks by neutrons

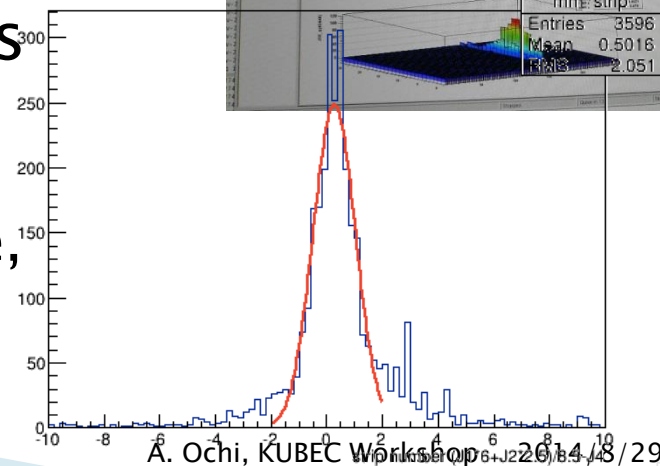
- ▶ No damage is observed on the resistive strips after neutron test



# Charged particle tracking



- ▶ Cosmic test using 4 MMs
  - At Kobe Univ, Sept. 2013
- ▶ 1.4GeV electron beam
  - At Spring-8 BL33 beamline, Nov. 2013



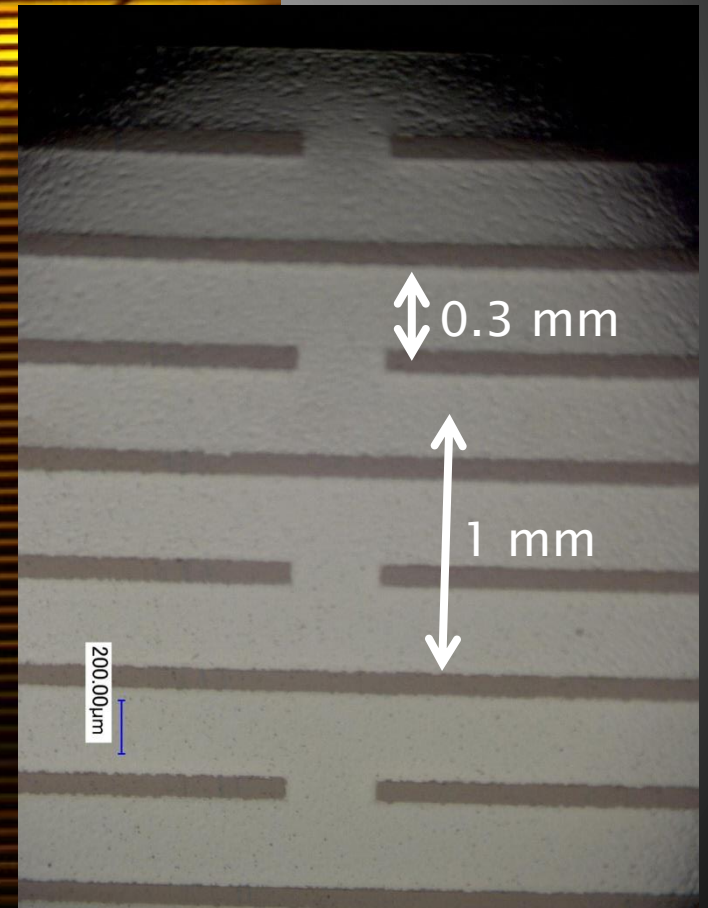
# Large resistive strip foil for MSW

866.4mm

425.3mm

# Enlarged picture of resistive strip foil

10 mm

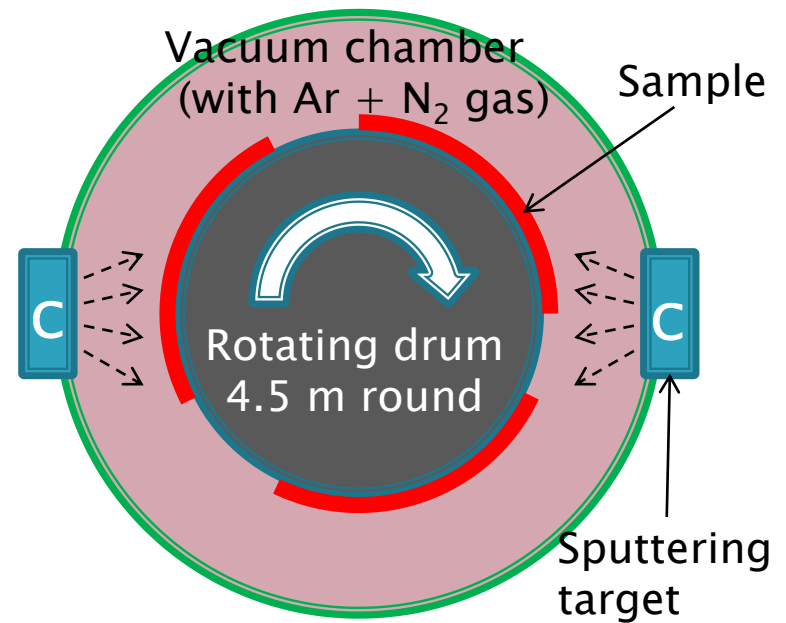


# Carbon sputtering further developments



# New idea: Nitrogen doping

- ▶ The structure of the sputtered carbon is amorphous diamond like carbon (a-DLC).
- ▶ It is thought that the charge carrier is very few in the DLC
- ▶ So, I got an idea of nitrogen doping as a supplier of carrier electrons.
  - This is same story as the n-type semiconductor production.
- ▶ The nitrogen is easy to introduce into the sputtering chamber with Argon gas.

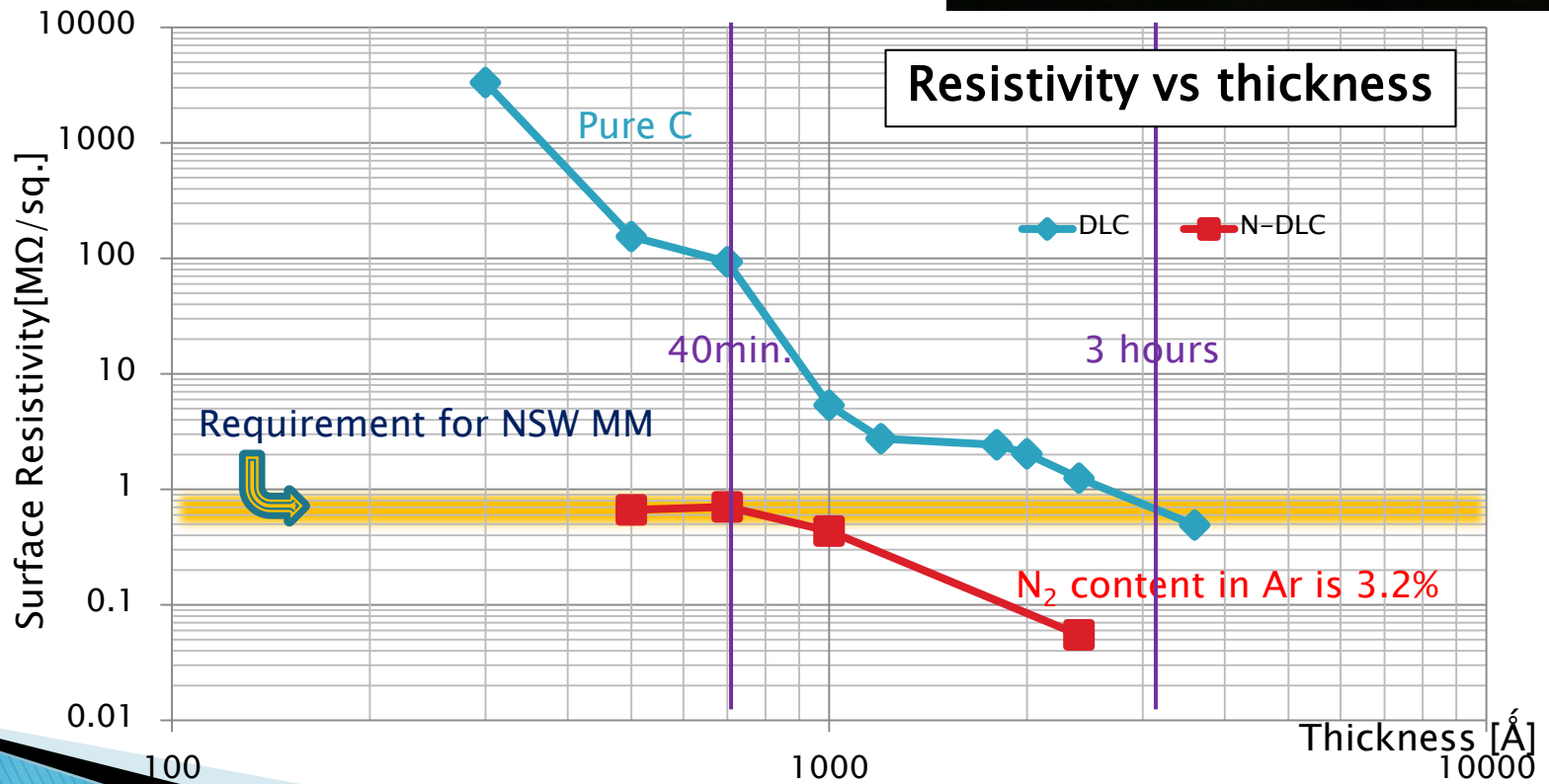
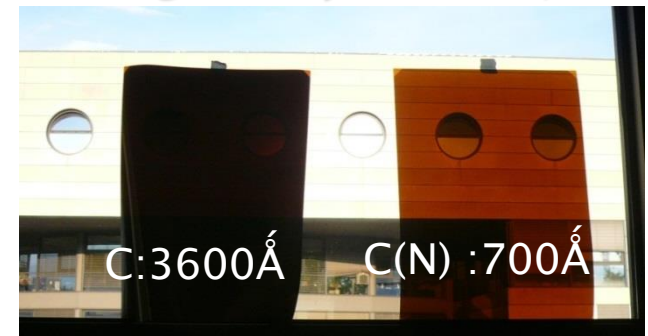


A periodic table is shown with a blue arrow labeled 'Dope' pointing from Carbon (C) to Nitrogen (N). Carbon (C) is circled in red, and Nitrogen (N) is highlighted in green. The table includes elements from Hydrogen (1) to Xenon (54).

					2 He
5 B	6 C	7 N	8 O	9 F	10 Ne
13 Al	14 Si	15 P	16 S	17 Cl	18 Ar
31 Ga	32 Ge	33 As	34 Se	35 Br	36 Kr
49 In	50 Sn	51 Sb	52 Te	53 I	54 Xe

# Resistivity vs thickness (June, 2014)

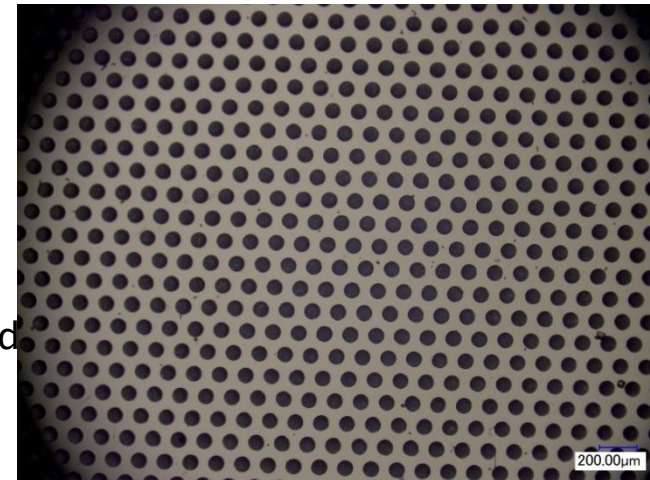
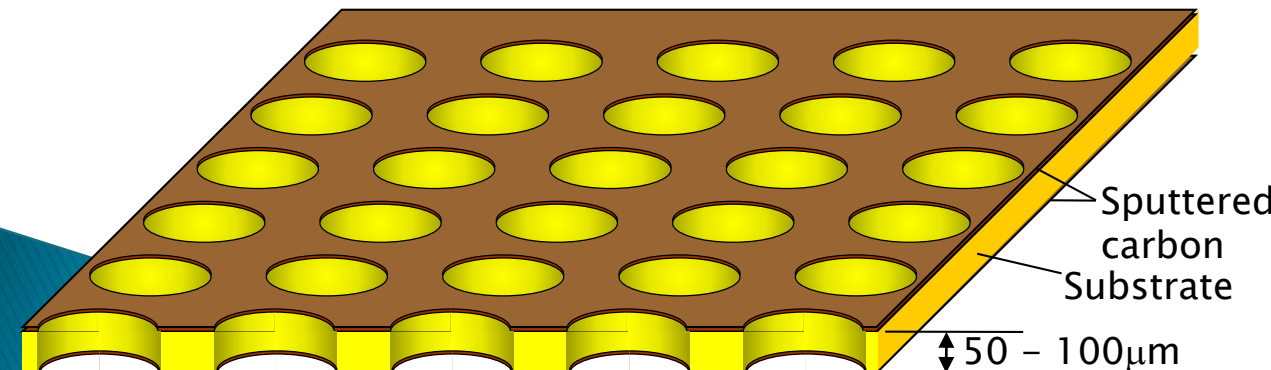
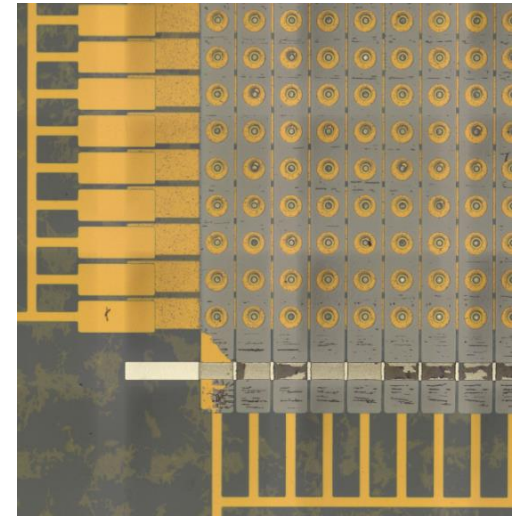
- ▶ For 3.2% N<sub>2</sub> content foils
  - 2400Å → 55kΩ/sq.
  - 700Å → 700kΩ/sq. (42min. sputter)





# Other MPGD development using carbon sputtering

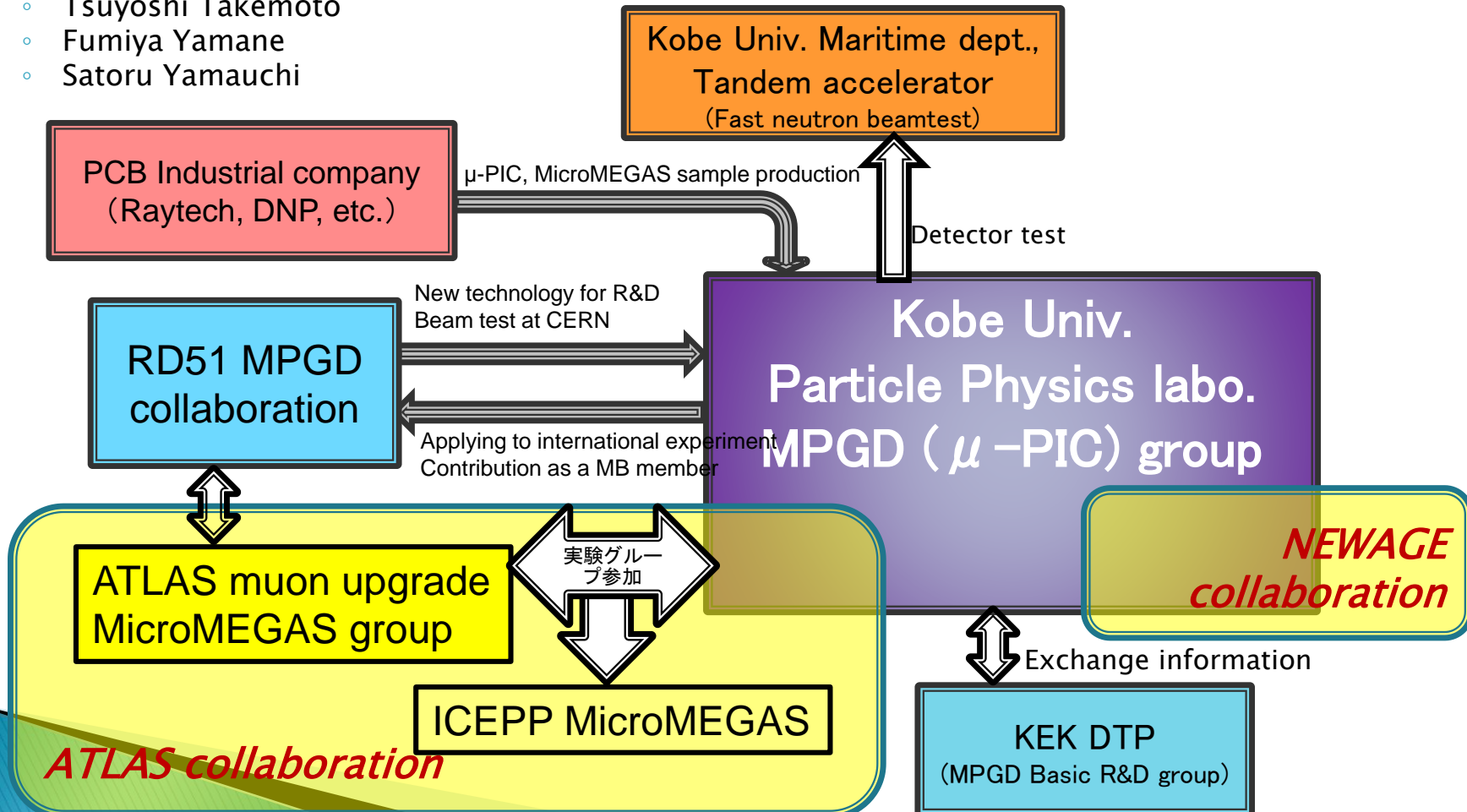
- ▶ Resistive  $\mu$ -PIC
  - New version using carbon sputtering is being tested
- ▶ Resistive GEM
  - The resistive electrodes are made by very thin (50 - 300nm) material
    - It will improve the signal gain
  - We have just made it, and it is being tested now.
    - (Scienergy + Raytech)



# Synergy of MPGD group

## ▶ Kobe MPGD group Member (2014)

- Atsuhiko Ochi
- Kentaro Miuchi
- Yasuhiro Homma
- Tsuyoshi Takemoto
- Fumiya Yamane
- Satoru Yamauchi



# Summary

- ▶ We are developing MPGDs as common technologies in particle physics experiments
  - MPGD with resistive electrodes
    - To suppress the electric discharge
  - $\mu$ -PIC : High rate  $\rightarrow$  ATLAS phase-II upgrade  
Low rate  $\rightarrow$  NEWAGE
  - MicroMEGAS : ATLAS NSW development
  - GEM : RE-GEM R&D has been started

Micro Pixel Chamber

